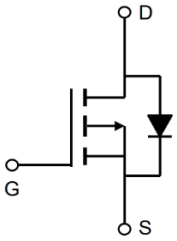
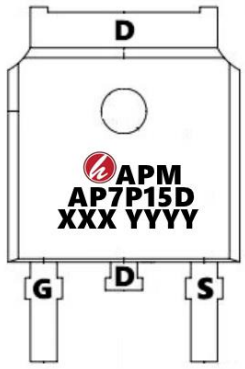
AP7P15D

-150V P-Channel Enhancement Mode MOSFET

Description

The AP7P15D uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.





General Features

V_{DS} = -150V I_D =-7A

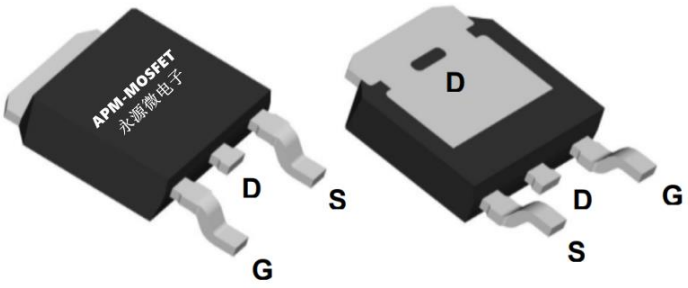
$R_{DS(ON)}$ < 780mΩ @ V_{GS}=10V **(Type：620mΩ)**

Application

Brushless motor

Load switch

Uninterruptible power supply



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP7P15D	TO-252-3L	AP7P15D XXX YYYY	2500

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	-150	V
VGS	Gate-Source Voltage	±20	V
I_D@T_A=25℃	Continuous Drain Current, -V_{GS} @ -10V[1]	-7.0	A
I_D@T_A=70℃	Continuous Drain Current, -V_{GS} @ -10V[1]	-4.8	A
IDM	Pulsed Drain Current[2]	-28	A
EAS	Single Pulse Avalanche Energy[3]	56.5	mJ
IAS	Avalanche Current	5	A
P_D@T_A=25℃	Total Power Dissipation[4]	2	W
TSTG	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃
$R_{\theta JA}$	Thermal Resistance Junction-Ambient [1]	62	℃/W
$R_{\theta JC}$	Thermal Resistance Junction-Case[1]	40	℃/W

P-Channel Electrical Characteristics (TJ =25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	VGS=0V , ID=-250uA	-150	-168	---	V
RDS(ON)	Static Drain-Source On-Resistance	VGS=-10V , ID=-1A	---	620	780	mΩ
RDS(ON)	Static Drain-Source On-Resistance	VGS=-6V , ID=-0.5A	---	700	980	
VGS(th)	Gate Threshold Voltage	VGS=VDS , ID =-250uA	-2.0	-3.0	-4.0	V
IDSS	Drain-Source Leakage Current	VDS=120V ,VGS=0V ,TJ=25℃	---	---	1	uA
IDSS	Drain-Source Leakage Current	VDS=120V ,VGS=0V ,TJ=85℃	---	---	30	uA
IGSS	Gate-Source Leakage Current	VGS=±20V , VDS=0V	---	---	±100	nA
Rg	Gate Resistance	VDS=0V , VGS=0V , f=1MHz	---	12	---	Ω
Qg	Total Gate Charge	VDS=-75V , VGS=-10V , ID=-1A	---	10.8	---	nC
Qgs	Gate-Source Charge		---	3.1	---	nC
Qgd	Gate-Drain Charge		---	2.2	---	nC
Td(on)	Turn-On Delay Time	VDD=-30V , VGS=-10V , RG=6Ω, ID=-1A	---	21	---	ns
Tr	Rise Time		---	16	---	ns
Td(off)	Turn-Off Delay Time		---	40	---	ns
Tf	Fall Time		---	18	---	ns
Ciss	Input Capacitance	VDS=-75V , VGS=0V , f=1MHz	---	706	---	pF
Coss	Output Capacitance		---	23	---	pF
Crss	Reverse Transfer Capacitance		---	13	---	pF

Note :
1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
2、The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%
3、The EAS data shows Max. rating . The test condition is VDD =-50V,VGS =-10V,L=0.5mH,IAS =-5A
4、The power dissipation is limited by 150℃ junction temperature
5、The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.

Typical Characteristics

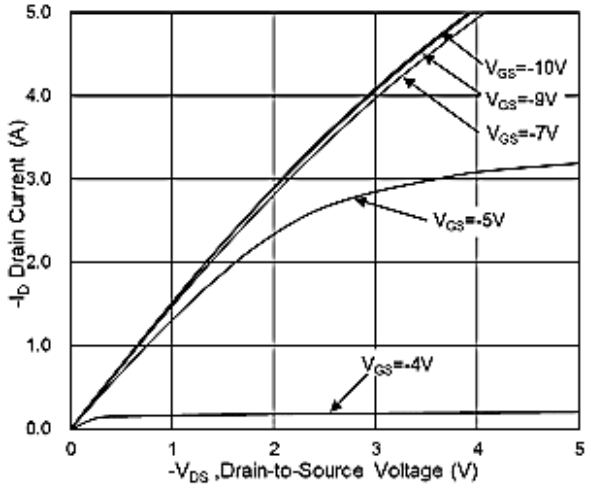


Fig.1 Typical Output Characteristics

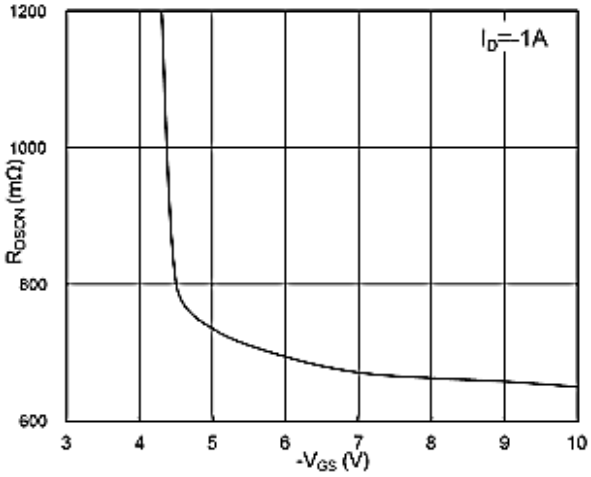


Fig.2 On-Resistance vs G-S Voltage

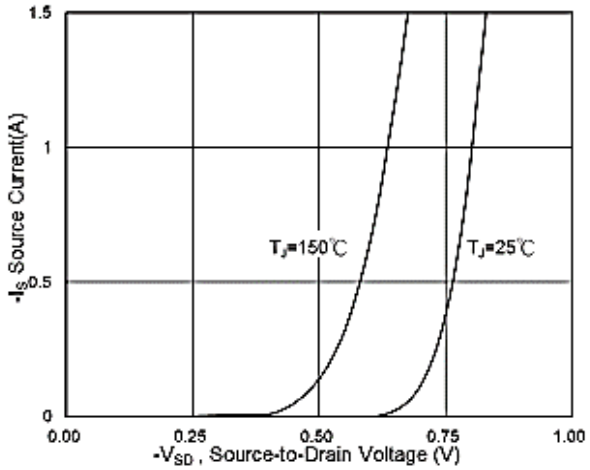


Fig.3 Source Drain Forward Characteristics

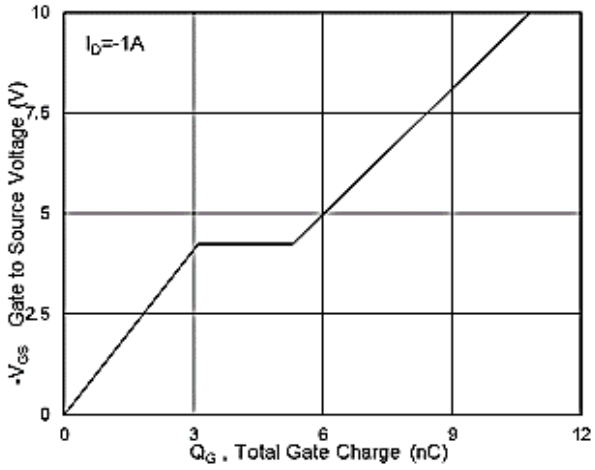


Fig.4 Gate-Charge Characteristics

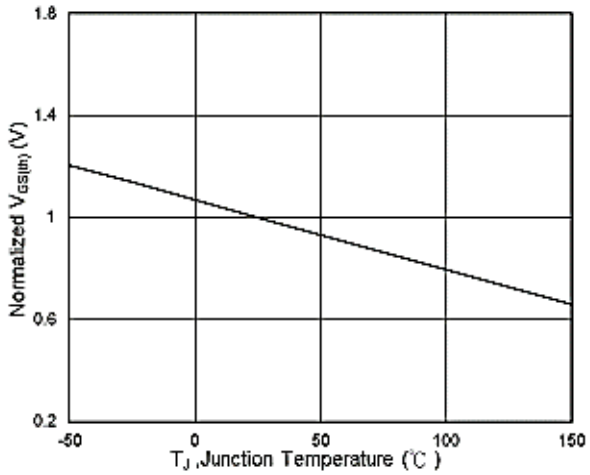


Fig.5 Normalized $V_{GS(th)}$ vs T_J

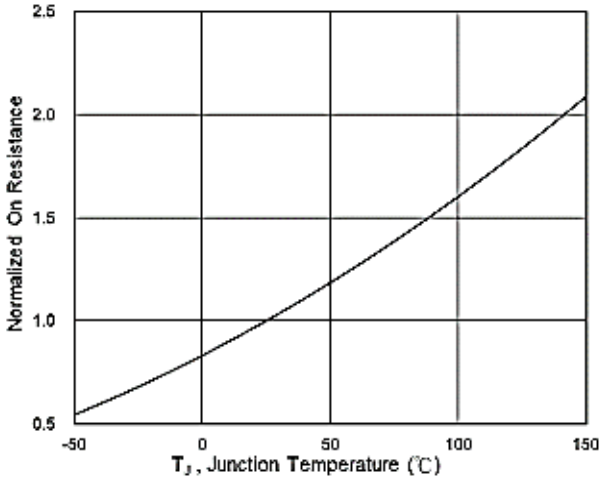


Fig.6 Normalized R_{DSON} vs T_J

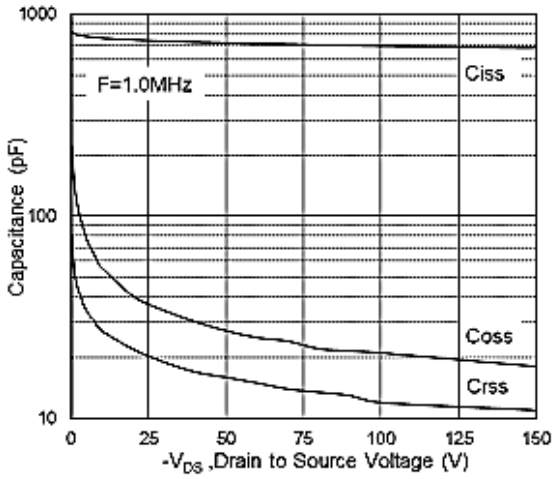


Fig.7 Capacitance

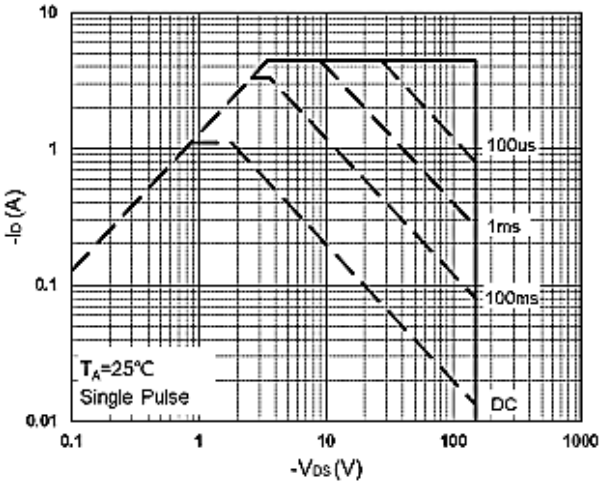


Fig.8 Safe Operating Area

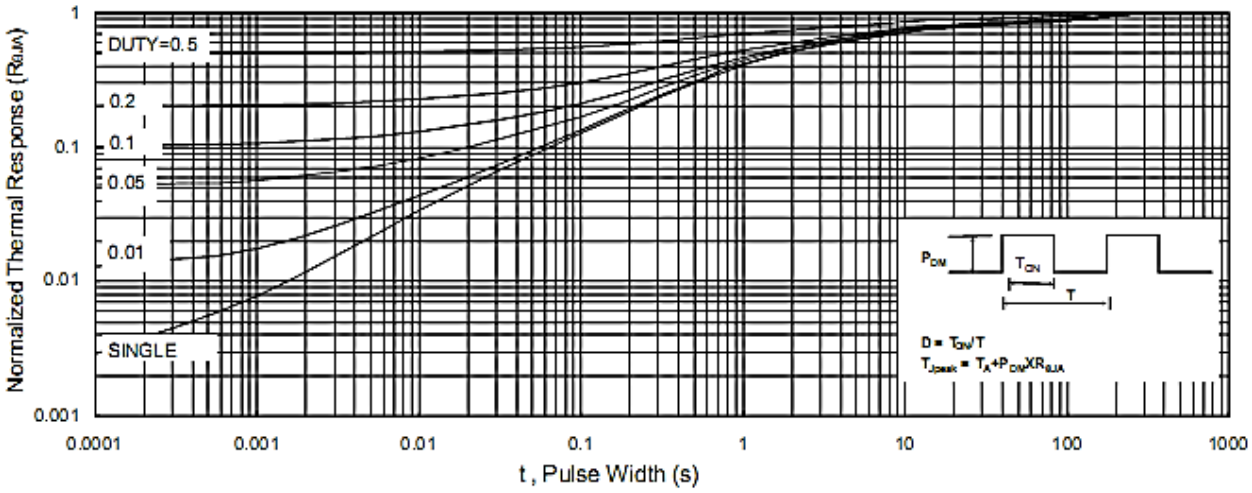


Fig.9 Normalized Maximum Transient Thermal Impedance

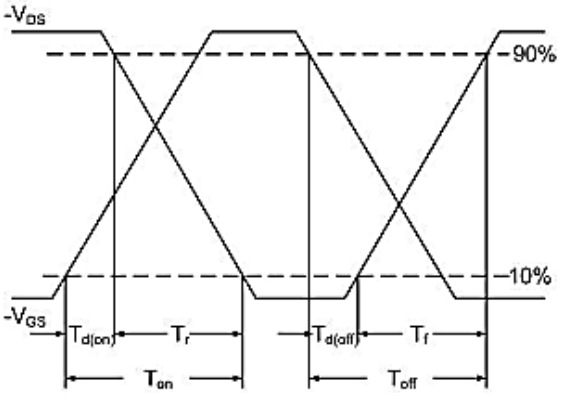


Fig.10 Switching Time Waveform

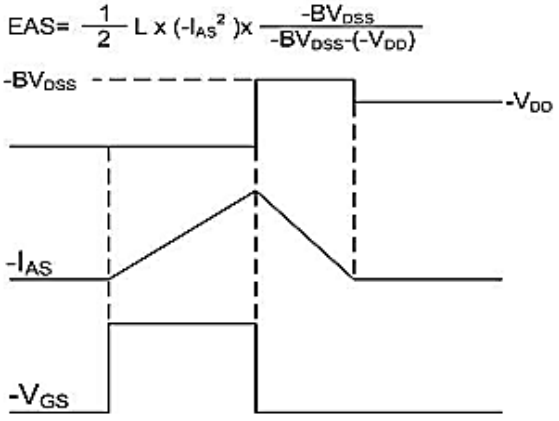
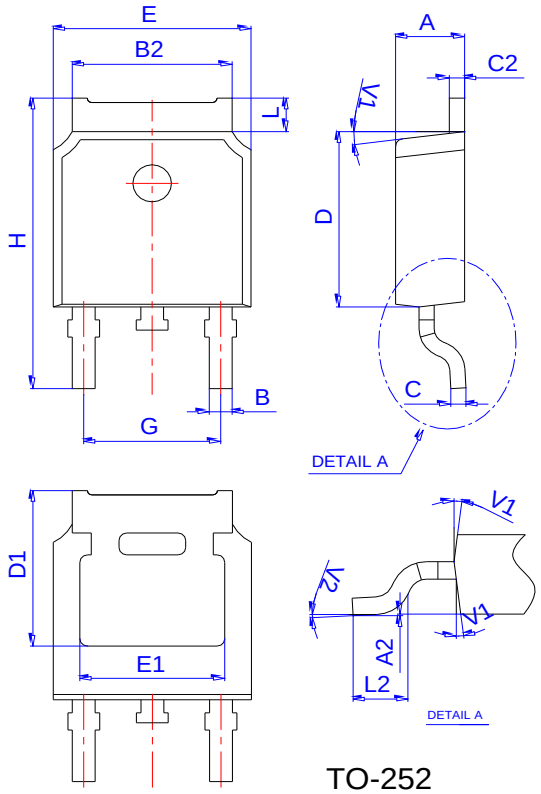


Fig.11 Unclamped Inductive Waveform

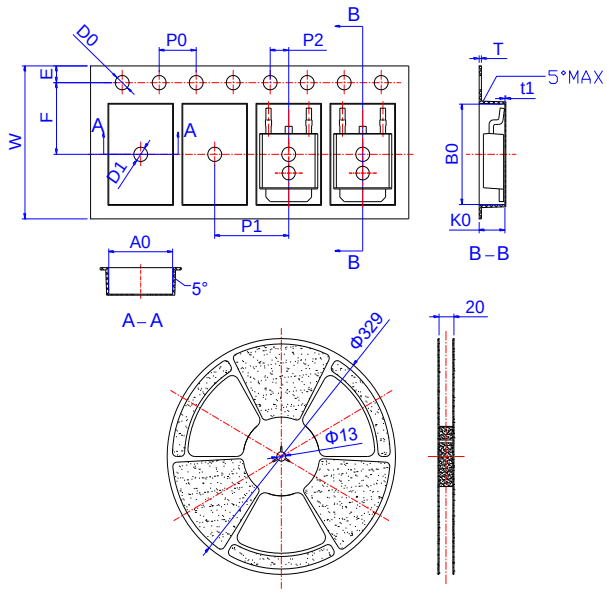
Package Mechanical Data:TO-252-3L



TO-252

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Reel Specification-TO-252



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583

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-150V P-Channel Enhancement Mode MOSFET

Edition	Date	Change
Rve1.0	2021/4/13	Initial release